



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

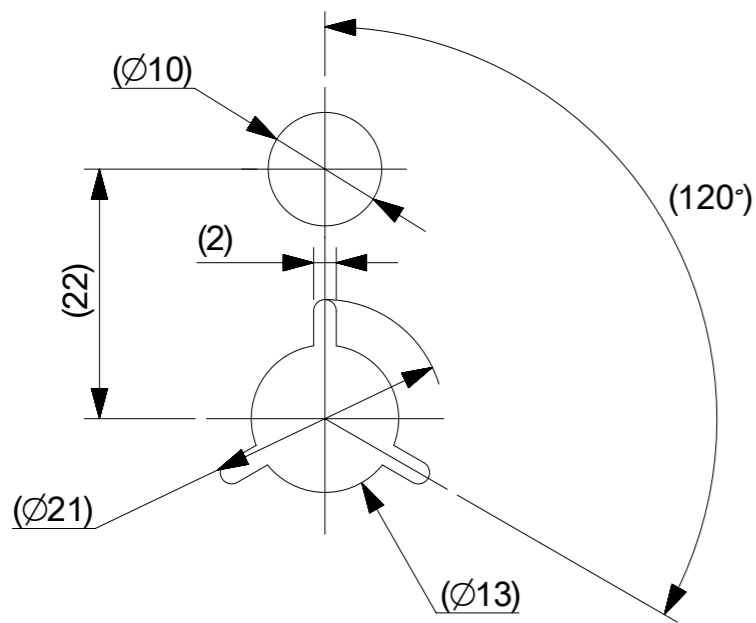
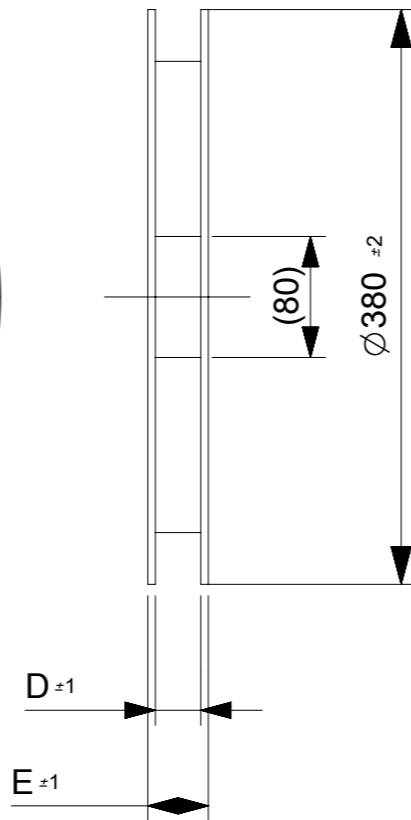
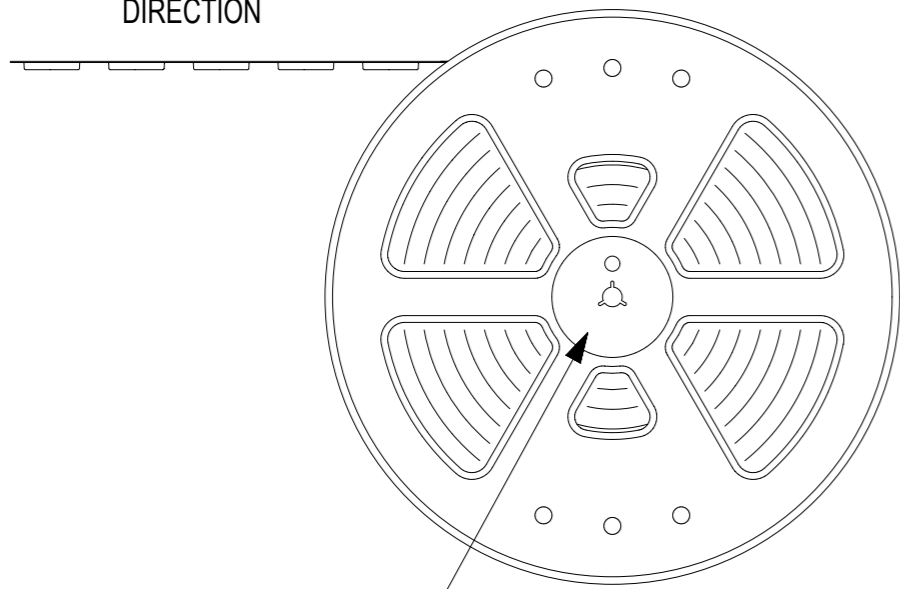
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



引き出し方向

PULL OUT DIRECTION



DETAIL "E"

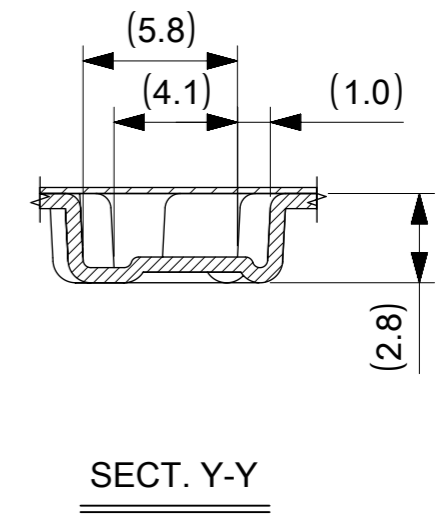
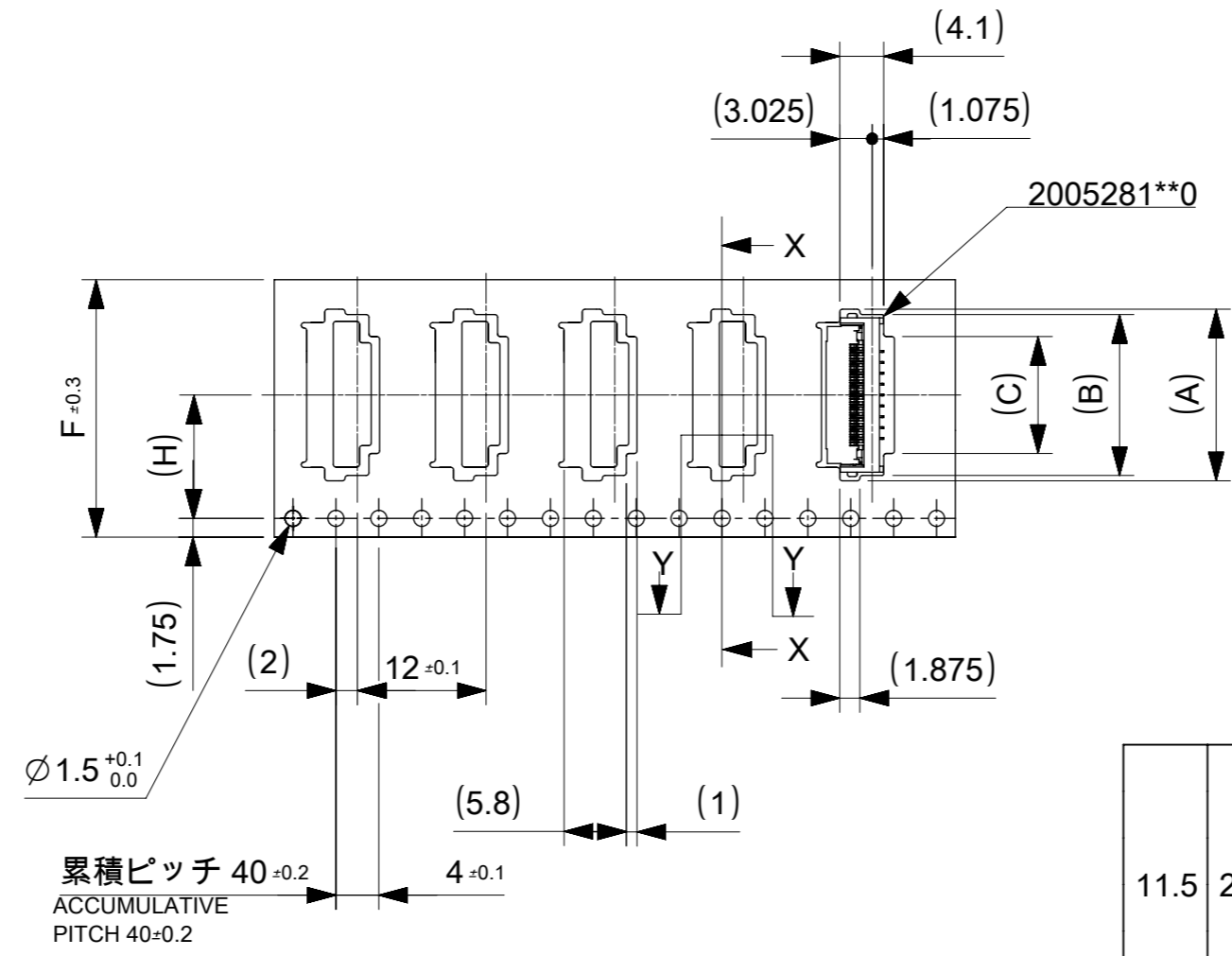
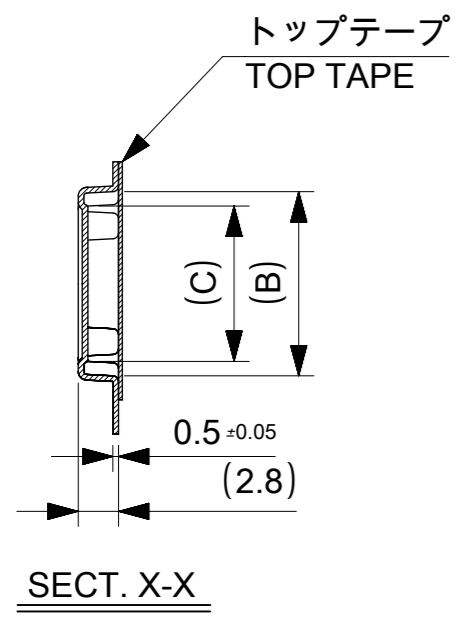
NOTES

- 梱包数量 : 3000個 / リール
NUMBER OF CONNECTORS : 3000 PCS/REEL.
 - リードテープ長さ
LEAD TAPE LENGTH
-
- カバーテープの剥離強度については、IEC60286-3に準拠。
COVER TAPE PEEL FORCE IS DEFINED BY IEC 60286-3.
 - 製品詳細寸法については、図面 2005281000-000を参照下さい。
FOR DIMENTIONS OF PRODUCT, REFER TO 2005281000-000.
 - 材料 MATERIAL
キャリアテープ : ポリスチレン
CARRIER TAPE : POLYSTYRENE
トップテープ : ポリエチレンテレフタレート、ポリエチレン
TOP TAPE : POLYETHYLENE TEREHTHALATE, POLYETHYLENE
リール :ポリスチレン<リサイクル材を含む>
 - ELV及びRoHS適合品 ELV AND RoHS COMPLIANT.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED	EC NO: 103009	2016/02/09	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	molex			
	DRWN: MTAKAHASHI04	2016/02/19	ANGULAR TOL ± 1.0 °	MM	2:1				
	CHK'D: KTAKAHASHI	2016/02/19	4 PLACES ± 0.05	DRWN BY	DATE	PRODUCT CUSTOMER DRAWING			
	APPR: TKUSUHARA01	2016/02/19	3 PLACES ± 0.1	MTAKAHASHI04	2015/12/22				
			2 PLACES ± 0.2	CHK'D BY	DATE	DOCUMENT NUMBER DOC TYPE DOC PART SHEET NUMBER 2005280000 PSD 000 1 OF 2			
		1 PLACE ± 0.2	KTAKAHASHI	2015/12/25					
		0 PLACES ± 0.2	APPR BY	DATE					
			YNOGAWA	2016/01/04					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION				
				A3					

引き出し方向
PULL OUT
DIRECTION



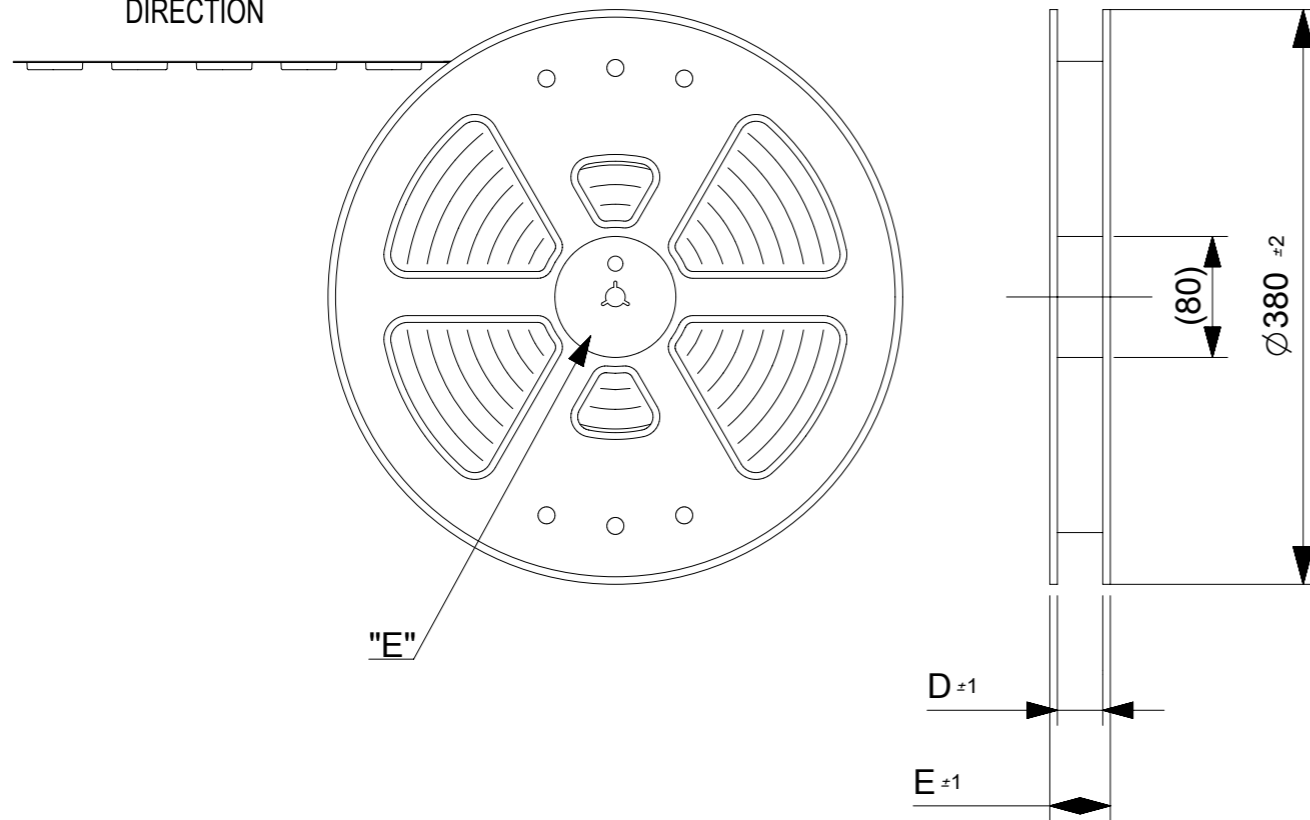
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				8.4	12.4	13.5	2005280070	7
				7.4	11.4	12.5	2005280060	6
				6.4	10.4	11.5	2005280050	5
				5.4	9.4	10.5	2005280040	4
H	F	E	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	Ckt
CONNECTER NO. 2005281**0								

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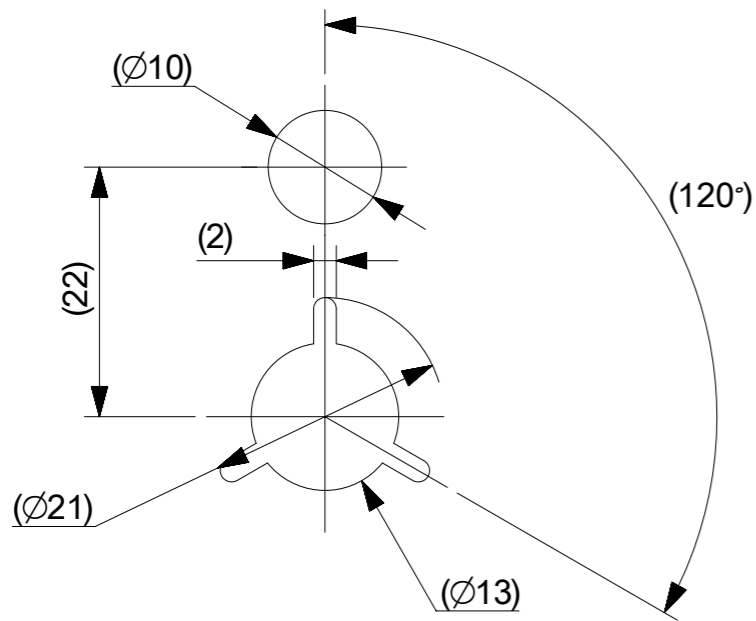
EC NO: 103009 DRWN: MTAKAHASHI04 CHK'D: KTAKAHASHI APPR: TKUSUHARA01	2016/02/09	2016/02/19	2016/02/19	GENERAL TOLERANCES (UNLESS SPECIFIED) ANGULAR TOL ± 1.0 ° 4 PLACES ± 0.05 3 PLACES ± 0.1 2 PLACES ± 0.2 1 PLACE ± 0.2 0 PLACES ± 0.2 DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION UNITS	SCALE						
	REVISED				MM	1:1						
	DRWN BY				DATE	MTAKAHASHI04		2015/12/22		1.0 FPC ZIF BTM 2 CONT EMBT PKG		
	CHK'D BY				DATE	KTAKAHASHI		2015/12/25				
	APPR BY				DATE	YNOGAWA		2016/01/04		PRODUCT CUSTOMER DRAWING		
DRAWING SIZE		THIRD ANGLE PROJECTION		A3				SERIES	MATERIAL NUMBER	CUSTOMER		
								200528	SEE CHART	GENERAL		
DOCUMENT NUMBER		DOC TYPE		DOC PART		SHEET NUMBER		2005280000		PSD	000	2 OF 2

引き出し方向

PULL OUT DIRECTION



"E"



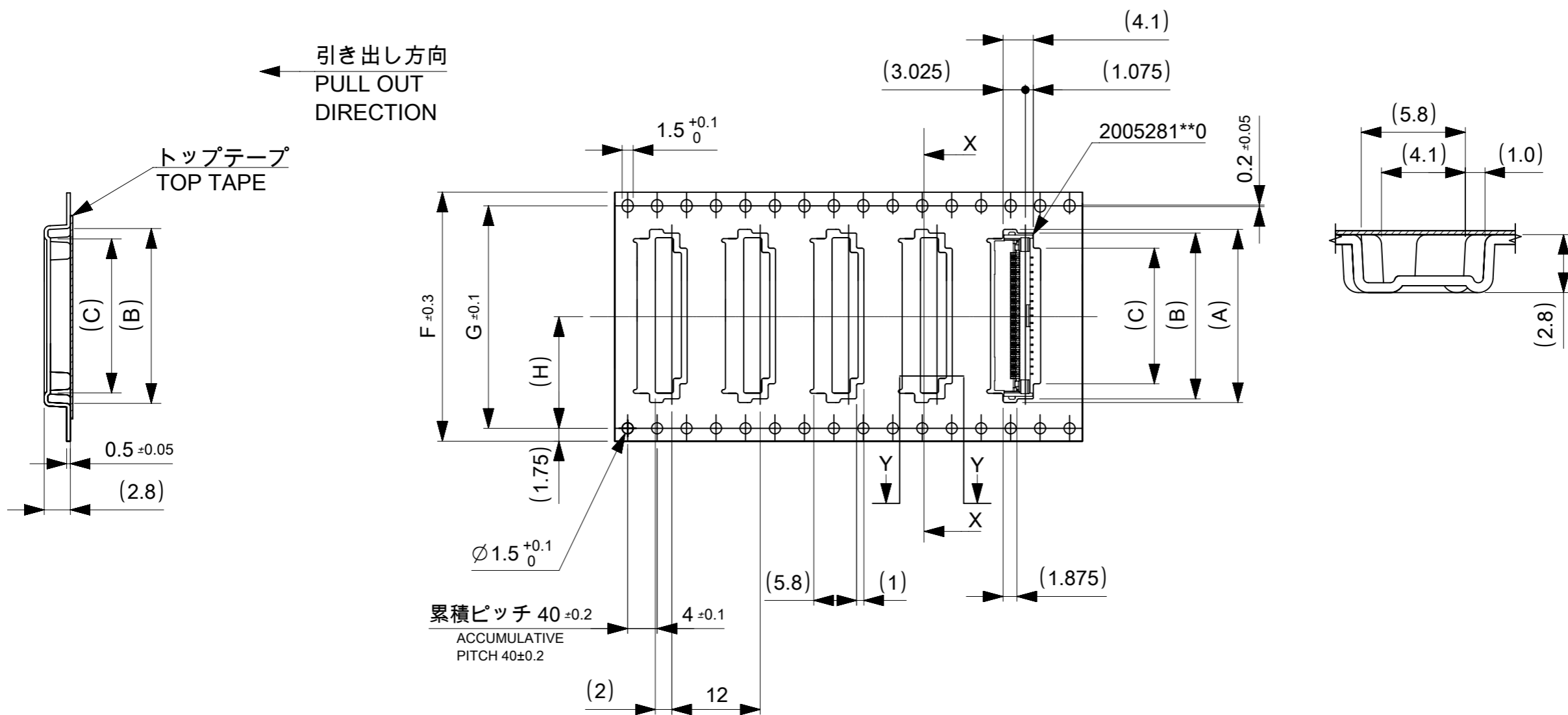
DETAIL "E"

NOTES

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キャリアテープ : ポリスチレン
CARRIER TAPE : POLYSTYRENE
トップテープ : ポリエチレンテレフタレート、ポリエチレン
TOP TAPE : POLYETHYLENE TEREHTHALATE, POLYETHYLENE
リール : ポリスチレン<リサイクル材を含む>
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REVISED	EC NO: 103009	2016/02/09	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	molex			
	DRWN: MTAKAHASHI04	2016/02/19	ANGULAR TOL ± 1.0 °	MM	2:1				
	CHK'D: KTAKAHASHI	2016/02/19	4 PLACES ± 0.05	DRWN BY	DATE	PRODUCT CUSTOMER DRAWING			
	APPR: TKUSUHARA01		3 PLACES ± 0.1	MTAKAHASHI04	2015/12/22				
			2 PLACES ± 0.2	KTAKAHASHI	2015/12/25	DOCUMENT NUMBER DOC TYPE DOC PART SHEET NUMBER 2005280006 PSD 000 1 OF 2			
		1 PLACE ± 0.2	YNOGAWA	2016/01/04					
		0 PLACES ± 0.2	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION				
				A3					

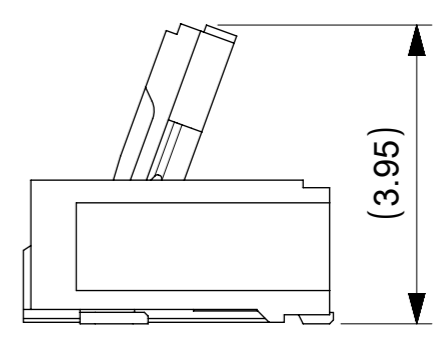
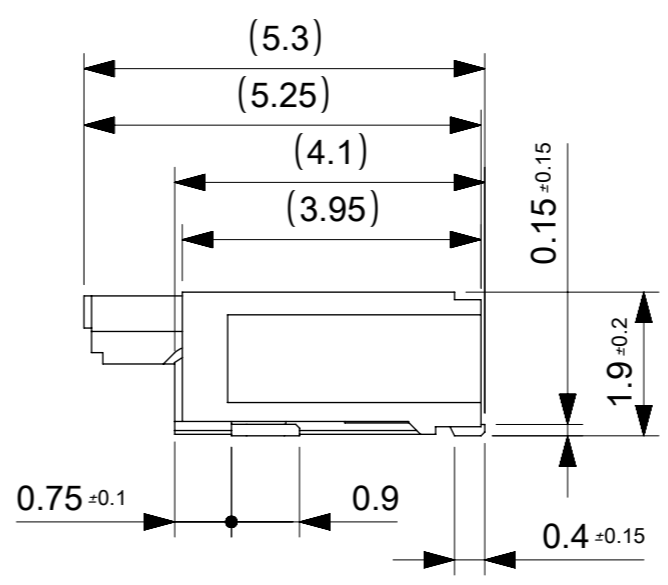
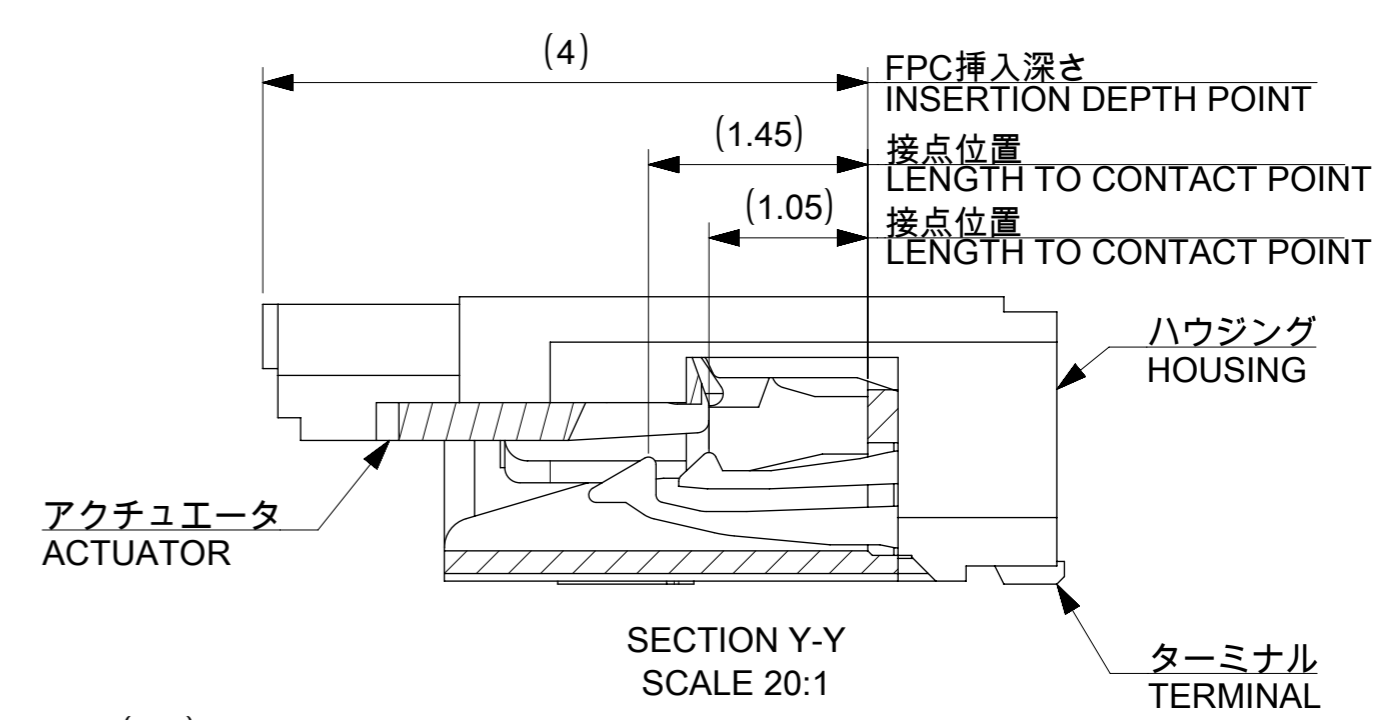
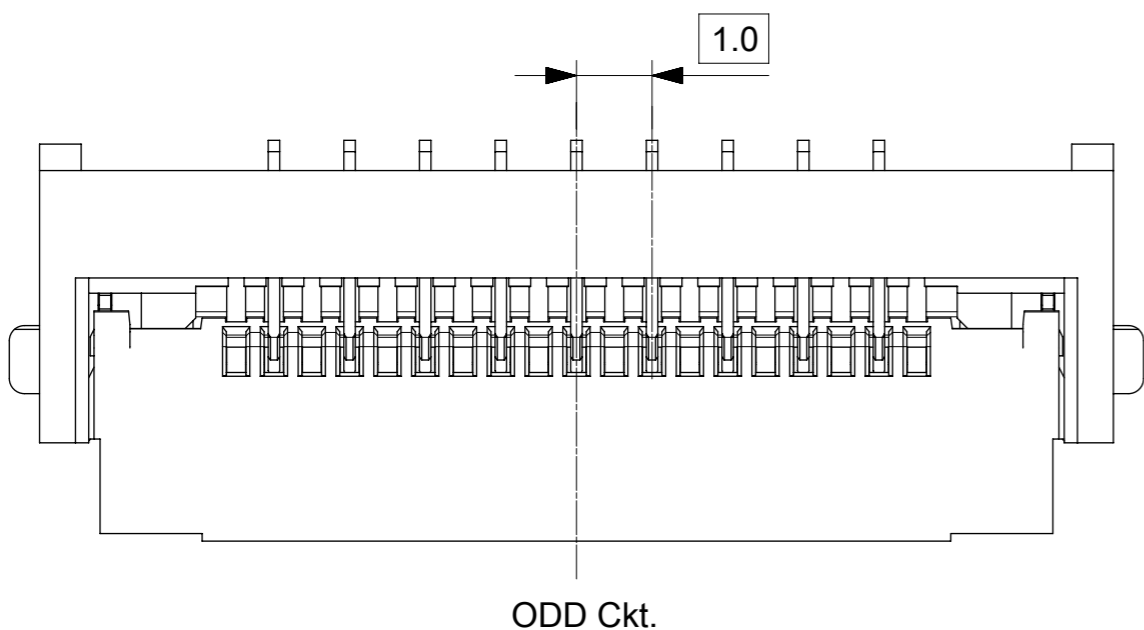
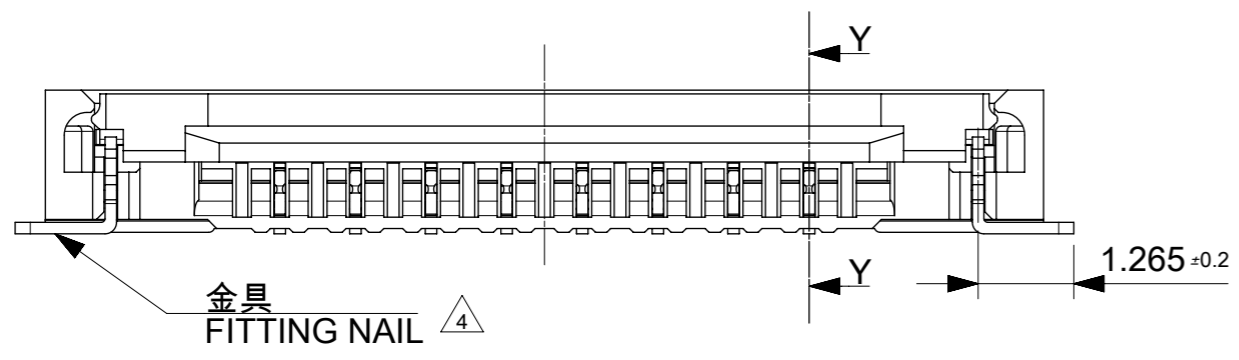
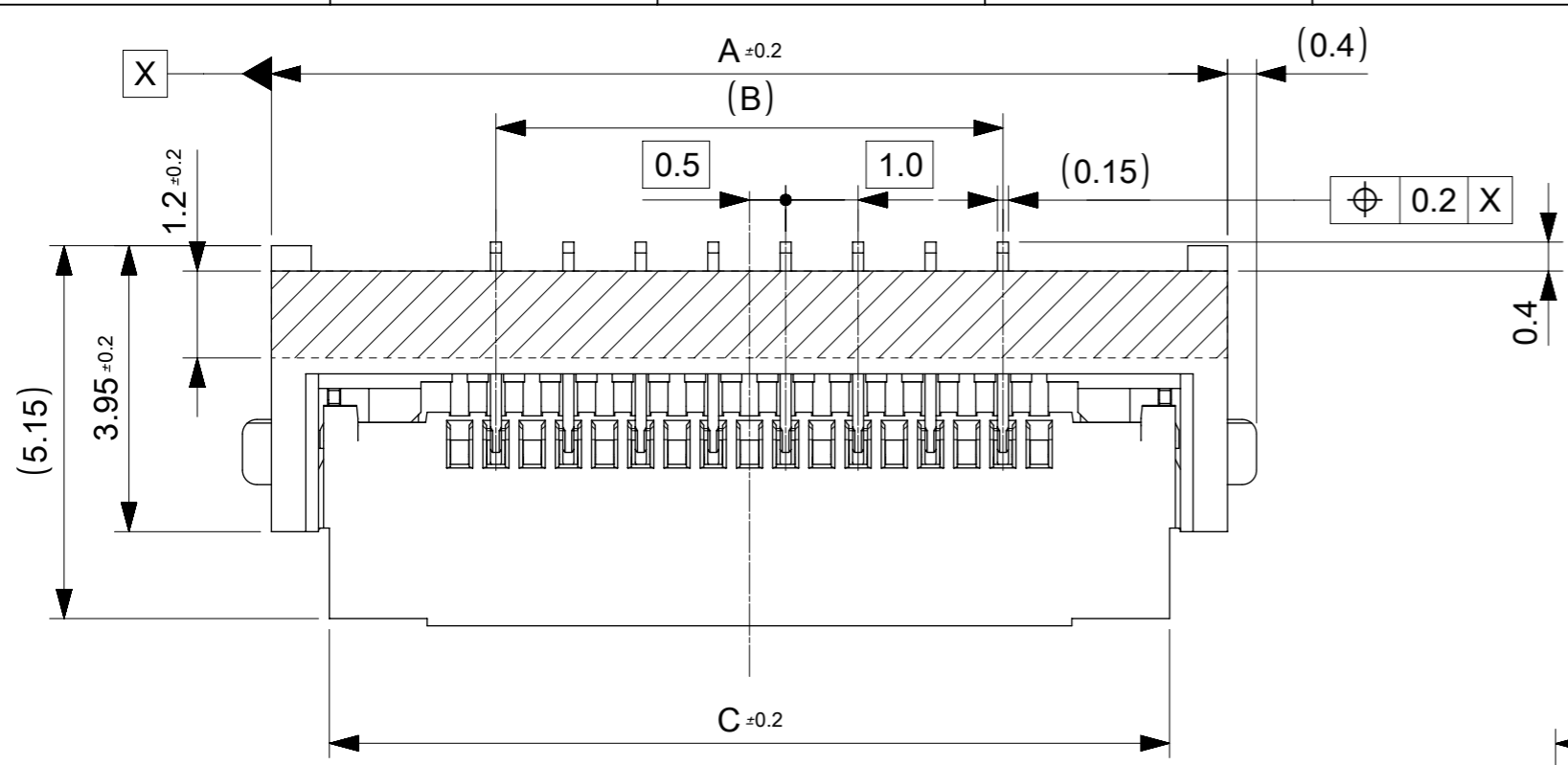


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H	G	F	E	D	C	B	A	EMBOSSED PACKAGE	Ckt
								オーダー番号 ORDER NO.	

CONNECTOR SERIES NO. 2005281**0

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EC NO: 103009 DRWN: MTAKAHASHI04 CHK'D: KTAKAHASHI APPR: TKUSUHARA01	2016/02/09	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE			
	2016/02/19	ANGULAR TOL ± 1.0 °	MM	2:1			
	2016/02/19	4 PLACES ± 0.05	DRWN BY	DATE		1.0 FPC ZIF BTM 2 CONT EMBT PKG	
		3 PLACES ± 0.1	MTAKAHASHI04	2015/12/22			
		2 PLACES ± 0.2	CHK'D BY	DATE		PRODUCT CUSTOMER DRAWING	
	1 PLACE ± 0.2	KTAKAHASHI	2015/12/25				
	0 PLACES ± 0.2	APPR BY	DATE	SERIES MATERIAL NUMBER CUSTOMER			
			YNOGAWA	2016/01/04	200528	SEE CHART	GENERAL
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION	DOCUMENT NUMBER DOC TYPE DOC PART SHEET NUMBER		
			A3		2005280006 PSD 000 2 OF 2		



12.6	8.0	14.2	2005280090	9
11.6	7.0	13.2	2005280080	8
10.6	6.0	12.2	2005280070	7
9.6	5.0	11.2	2005280060	6
8.6	4.0	10.2	2005280050	5
7.6	3.0	9.2	2005280040	4
C	B	A	EMBOSSED PACKAGE	Ckt
			オーダー番号 ORDER NO.	

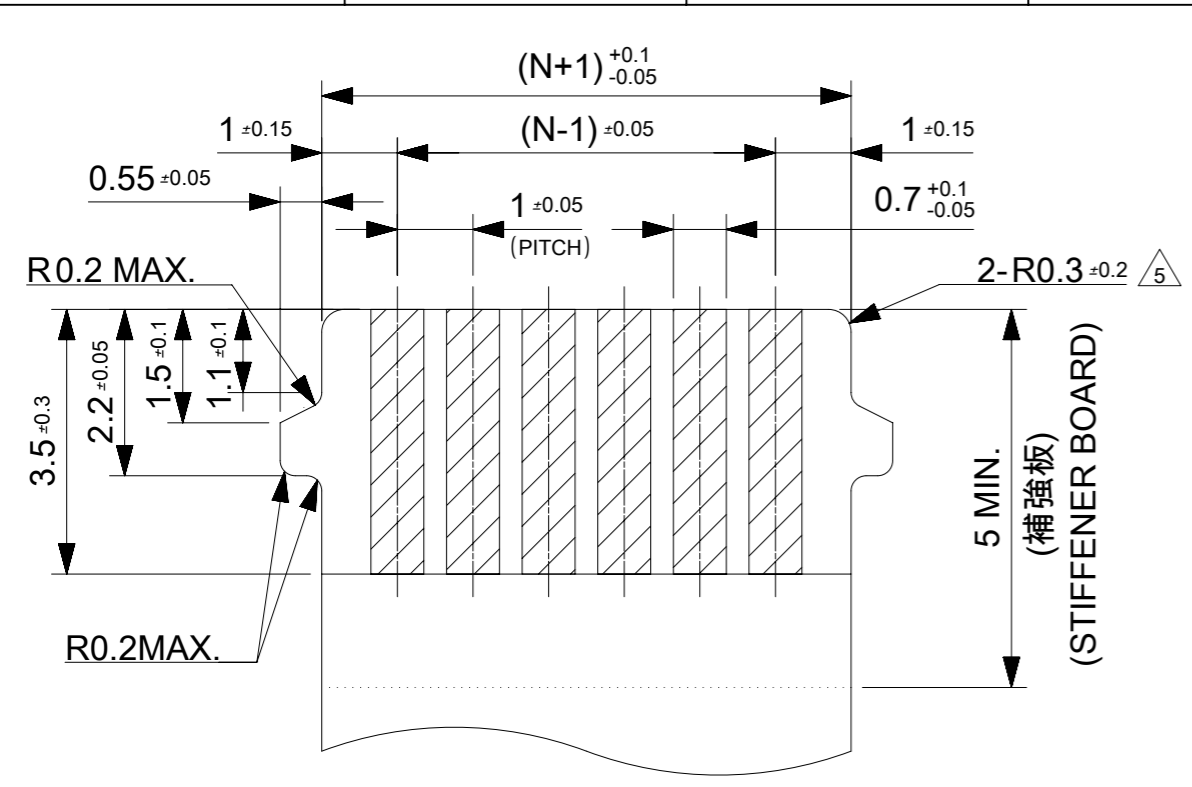
CONNECTOR SERIES NO.2005281**0

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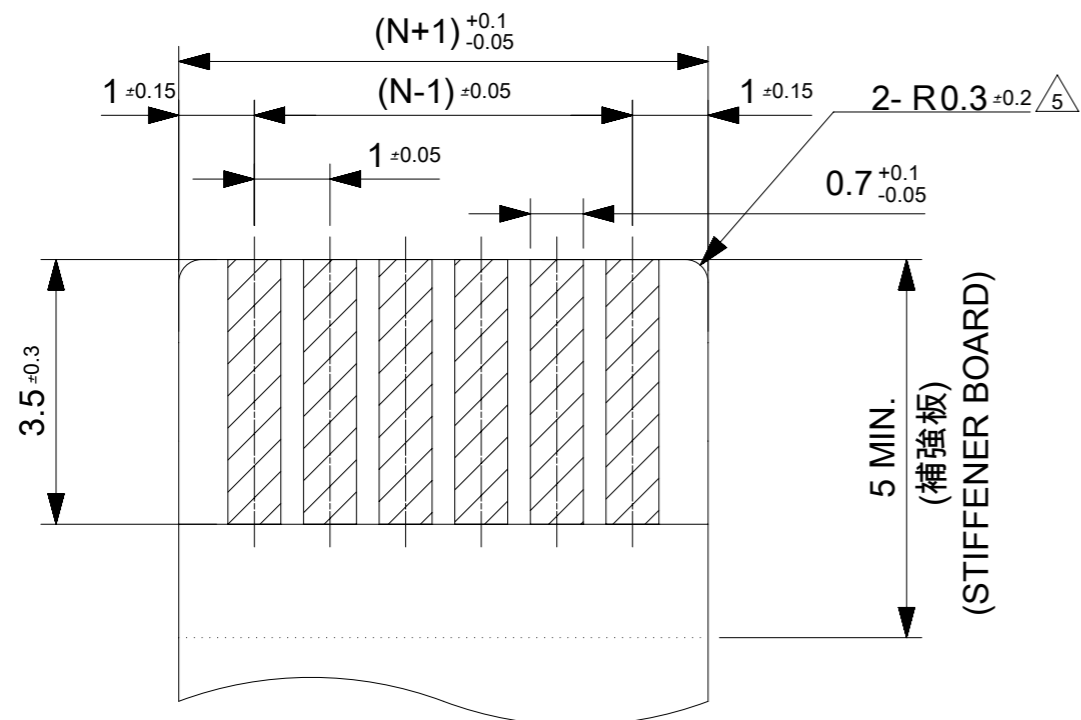
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		3 PLACES ± 0.1	MTAKAHASHI04	2015/12/21	
	2 PLACES ± 0.2	CHK'D BY	DATE		
	1 PLACE ± 0.2	KTAKAHASHI	2015/12/25		
	0 PLACES ± 0.2	APPR BY	DATE		
		YNOGAWA	2016/01/04		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION	
			A3		

EC NO: 103009	DRWN: MTAKAHASHI04	CHK'D: KTAKAHASHI	APPR: TKUSUHARA01
RELEASE STATUS	P1	RELEASE DATE	19.02.2016 08:41:14
SERIES	MATERIAL NUMBER	CUSTOMER	
200528	SEE CHART	GENERAL	
DOCUMENT NUMBER	DOC TYPE	DOC PART	SHEET NUMBER
2005281000	PSD	000	1 OF 3

適合FPC/FFC推奨寸法
APPLICABLE FPC/FFC
RECOMMENDED DIMENSION



耳無し適合FPC/FFC推奨寸法
APPLICABLE NON-TAB FPC/FFC
RECOMMENDED DIMENSION



補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE

熱硬化接着剤
THERMOSETTING ADHESIVE

ベースフィルム: ポリイミド(25μm)
BASE FILM: POLYIMIDE(25μm)

熱硬化接着剤
THERMOSETTING ADHESIVE

導体部: 銅箔(35μm)
CONDUCTOR: COPPER FOIL (35μm)

熱硬化接着剤
THERMOSETTING ADHESIVE

カバーレイ: ポリイミド(25μm)
COVER FILM: POLYIMIDE(25μm)

めっき: 金めっき(0.2 μm)
下地ニッケル(1-5μm)
PLATING: GOLD(0.2μm)
NICKEL UNDER(1-5μm)

補強板: ポリエステル系
REINFORCE BOARD: PET

接着剤(難燃ポリエステル系)
ADHESIVE (FLAME-RETARDANT
POLYESTER ADHESIVE)

絶縁テープ: ポリエステル系(25μm)
INSULATING FILM: PET(25μm)

接着剤(難燃ポリエステル系)
ADHESIVE (FLAME-RETARDANT
POLYESTER ADHESIVE)

導体部: 銅箔(35μmか50μm)
CONDUCTOR: COPPER FOIL (35μm or 50μm)

熱硬化接着剤
THERMOSETTING ADHESIVE

絶縁テープ: ポリエステル系(25μm)
INSULATING FILM: PET(25μm)

めっき: 金めっき(0.2 μm)
下地ニッケル(1-5μm)
PLATING: GOLD(0.2μm)
NICKEL UNDER(1-5μm)

補強板: ポリエステル系
REINFORCE BOARD: PET

接着剤(難燃ポリエステル系)
ADHESIVE (FLAME-RETARDANT
POLYESTER ADHESIVE)

絶縁テープ: ポリエステル系(25μm)
INSULATING FILM: PET(25μm)

めっき: 金めっき(0.2 μm)
下地ニッケル(1-5μm)
PLATING: GOLD(0.2μm)
NICKEL UNDER(1-5μm)

FPC構成推奨仕様
STRUCTURE OF FPC

FFC構成推奨仕様
STRUCTURE OF FFC

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REVISED	2016/02/09	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE
	2016/02/19	ANGULAR TOL ± 1.0 °	MM	##
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		3 PLACES ± 0.1	MTAKAHASHI04	2015/12/21
		2 PLACES ± 0.2	CHK'D BY	DATE
	1 PLACE ± 0.2	KTAKAHASHI	2015/12/25	
	0 PLACES ± 0.2	APPR BY	DATE	
		YNOGAWA	2016/01/04	
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION
			A3	

molex			
1.0 FPC ZIF BTM 2 CONT HSG ASSY			
PRODUCT CUSTOMER DRAWING			
SERIES	MATERIAL NUMBER	CUSTOMER	
200528	SEE SHEET 1	GENERAL	
DOCUMENT NUMBER		DOC TYPE	DOC PART SHEET NUMBER
2005281000		PSD	000 2 OF 3

注記 NOTES

1.使用材料 MATERIAL

ハウジング :液晶ポリマー ガラス充填、UL94V-0(ベージュ)
 HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)
 アクチュエータ :ポリアミド ガラス充填、UL94V-0(黒)
 ACTUATOR POLYAMIDE GLASS FILLED, UL94V-0(BLACK)
 ターミナル :リン青銅(t=0.15)
 TERMINAL PHOSPHOR BRONZE
 金具 :リン青銅(t=0.15)
 FITTING NAIL PHOSPHOR BRONZE

2.めっき仕様 PLATING

ターミナル TERMINAL
 コンタクト部 : 部分金めっき (0.05μm以上)
 テール部 : 部分金めっき
 下地:ニッケルめっき (1.0μm以上)
 CONTACT AREA : SEPARATED GOLD PLATING (0.05 MICROMETER MINIMUM)
 SOLDER TAIL AREA : SEPARATED GOLD PLATING
 UNDERPLATE : NICKEL OVERALL (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 錫めっき(1.0μm以上)
 下地:ニッケルめっき (1.0μm以上)
 TIN PLATING (1.0 MICROMETER MIN.)
 UNDER PLATING : NICKEL PLATING (1.0 MICROMETER MIN.)

3.エンボステープ梱包時は、アクチュエータが閉じた状態とする。
 IN THE PACKAGE, ACTUATOR OF PART SHOULD BE CLOSED.

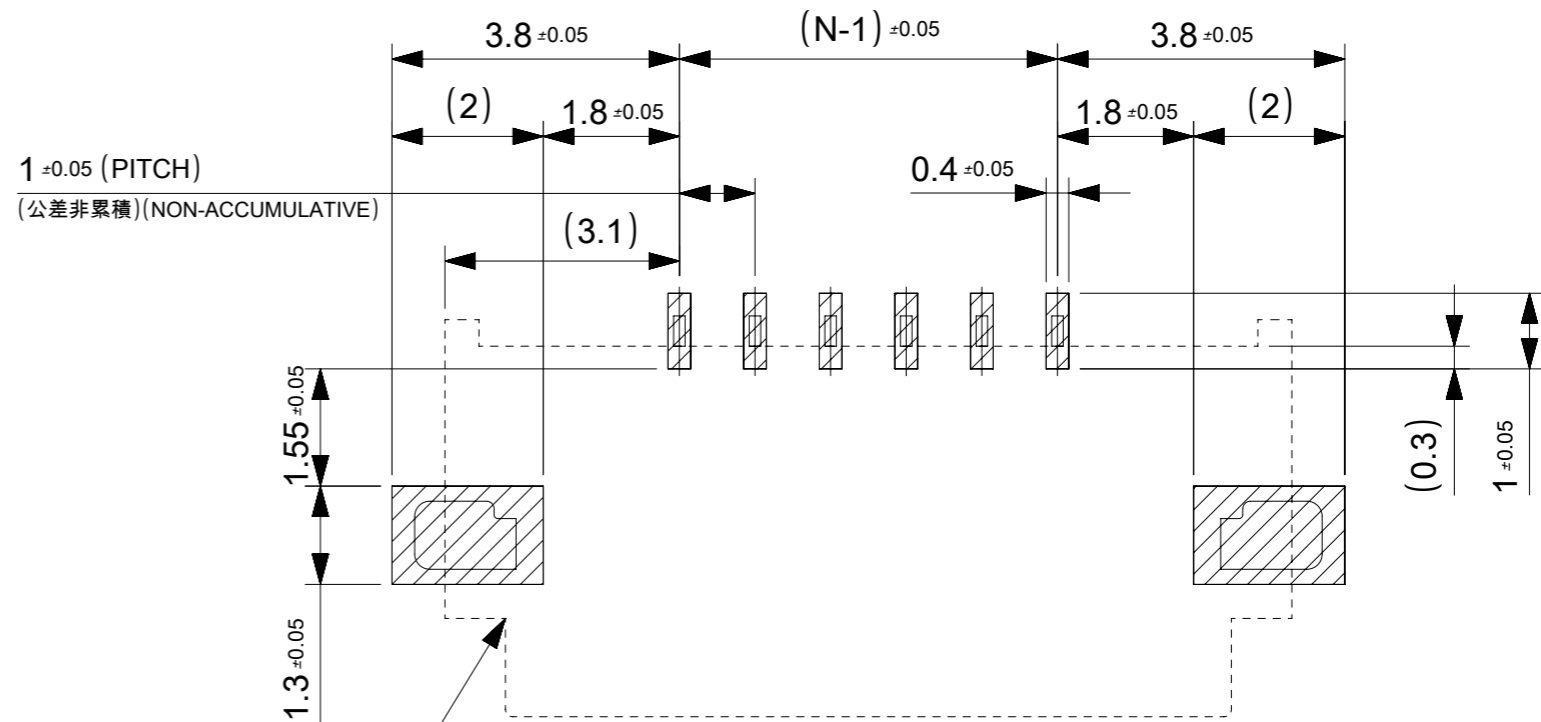
4. パターン剥離止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

5. R0.3はFPC/FFC導体部にかからないこと。
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC/FFC.

6.N:極数 N:CIRCUIT.

7.ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

8.テールと金具を併せた平坦度は0.1以下とする。
 TAILS AND NAILS COPLANALITY TO BE 0.1 MAX.



コネクタ位置
 (CONNECTOR POSITION)

推奨基板レイアウト
 RECOMENDED P.W.B.
 PATTERN LAYOUT

参考マスク厚 : 100μm
 参考マスク開口率 : 100%
 REFERENCE SCREEN THICKNESS : 100μm
 REFERENCE SCREEN OPEN RATIO : 100%

FPC/FFCについて ABOUT FPC/FFC

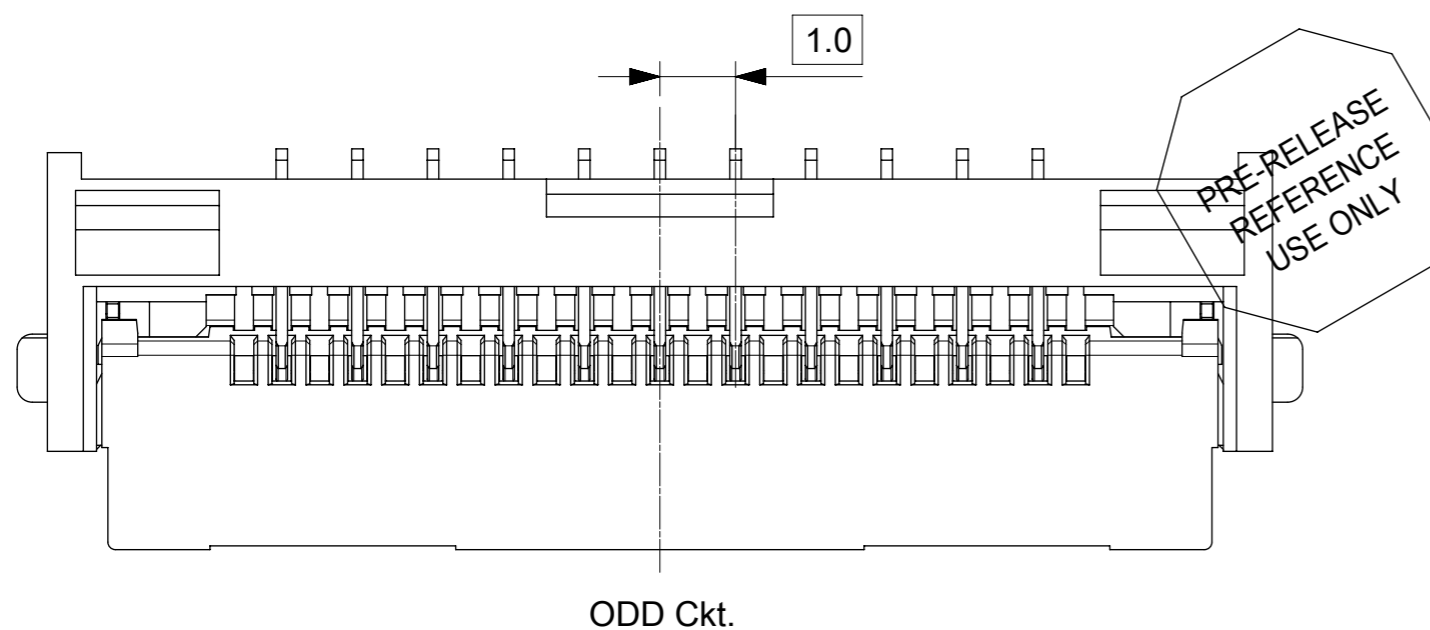
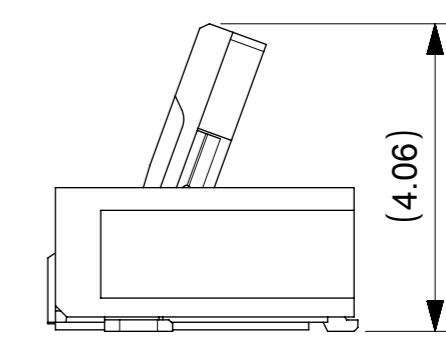
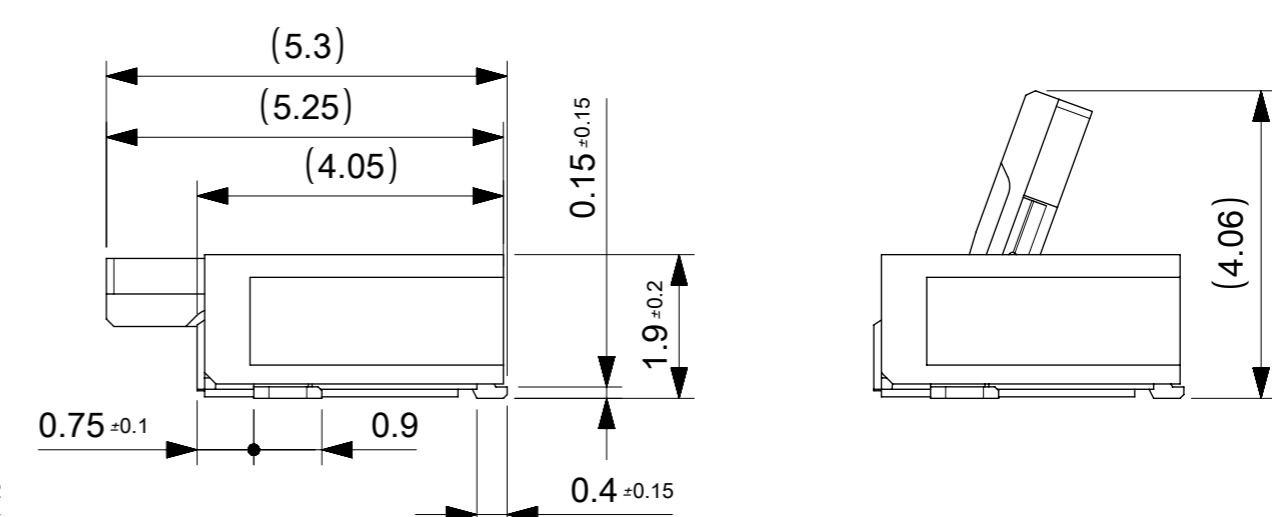
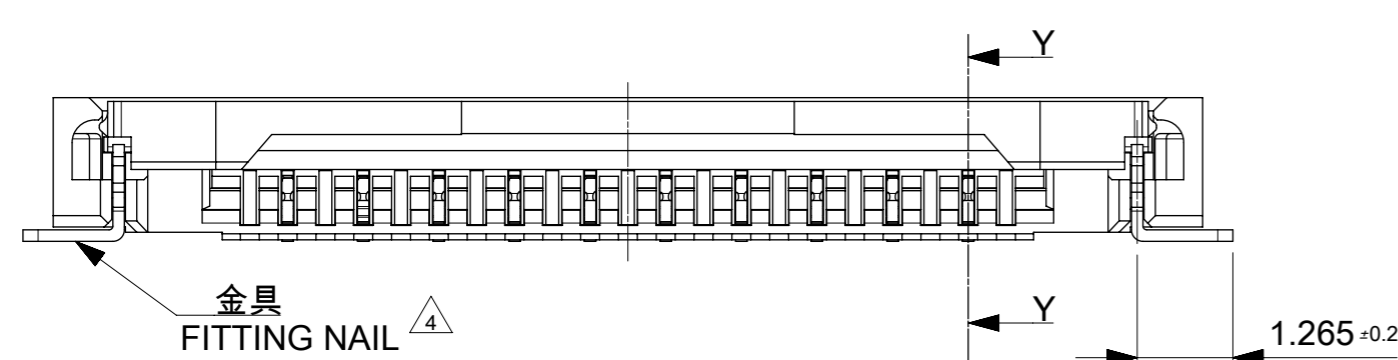
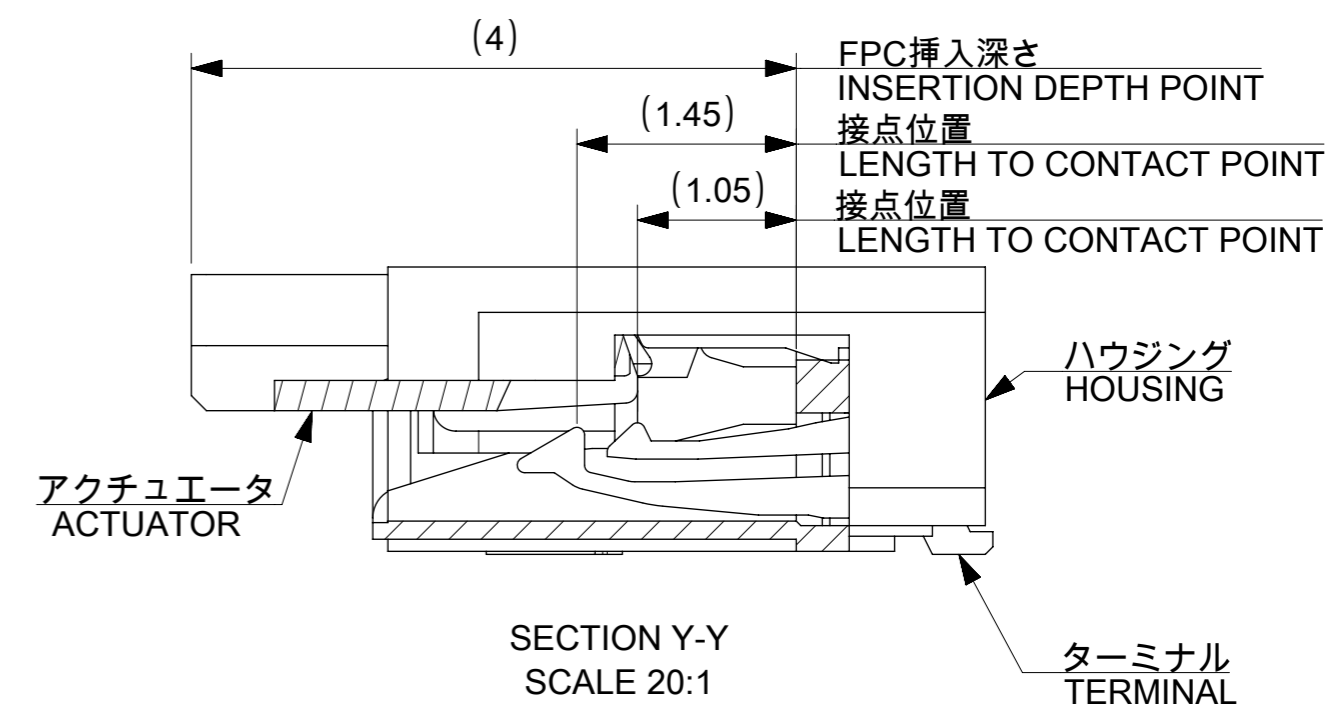
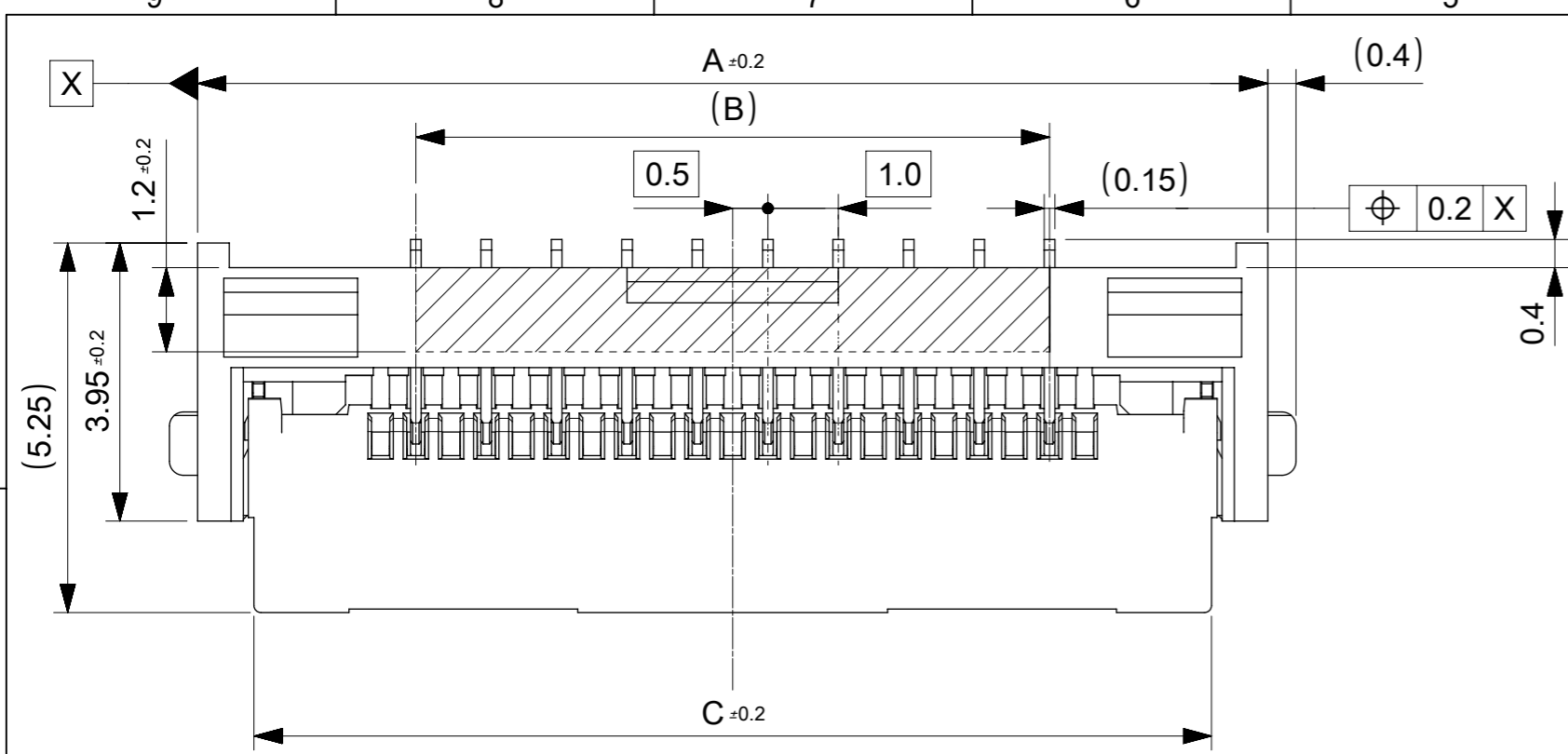
打ち抜き方向は導体側から補強板側を推奨します。
 導体部については軟箔銅35μmまたは50μmを推奨します。
 FFCに規定された定格温度がFFC単体前提である場合が御座います。
 コネクタと組み合わせての実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避するため、
 実機での評価/確認をお願いいたします。
 RECOMMENDED PUNCHING DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC : SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS : 35 MICROMETER OR 50 MICROMETER
 WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

FPCについて ABOUT FPC

補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。
 RECOMMENDED MATERIAL/THICKNESS.
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
 THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.

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		3 PLACES ± 0.1	MTAKAHASHI04	2015/12/21	
		2 PLACES ± 0.2	CHK'D BY	DATE	
	1 PLACE ± 0.2	KTAKAHASHI	2015/12/25		1.0 FPC ZIF BTM 2 CONT HSG ASSY PRODUCT CUSTOMER DRAWING
	0 PLACES ± 0.2	APPR BY	DATE		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	YNOGAWA	2016/01/04		
		DRAWING SIZE	THIRD ANGLE PROJECTION		
		A3			SERIES: 200528 MATERIAL NUMBER: SEE SHEET 1 CUSTOMER: GENERAL
					DOCUMENT NUMBER: 2005281000 DOC TYPE: PSD DOC PART: 000 SHEET NUMBER: 3 OF 3

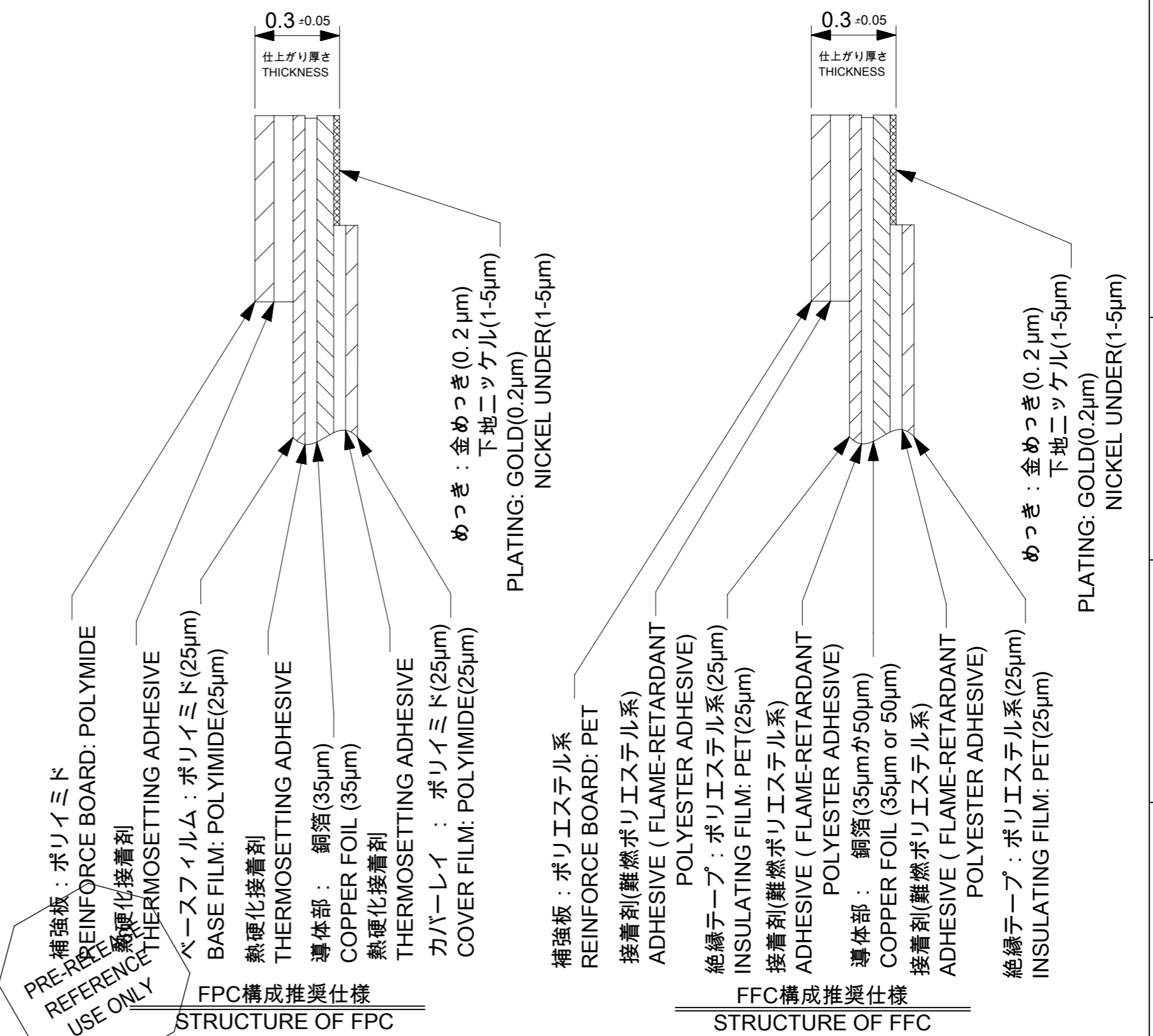
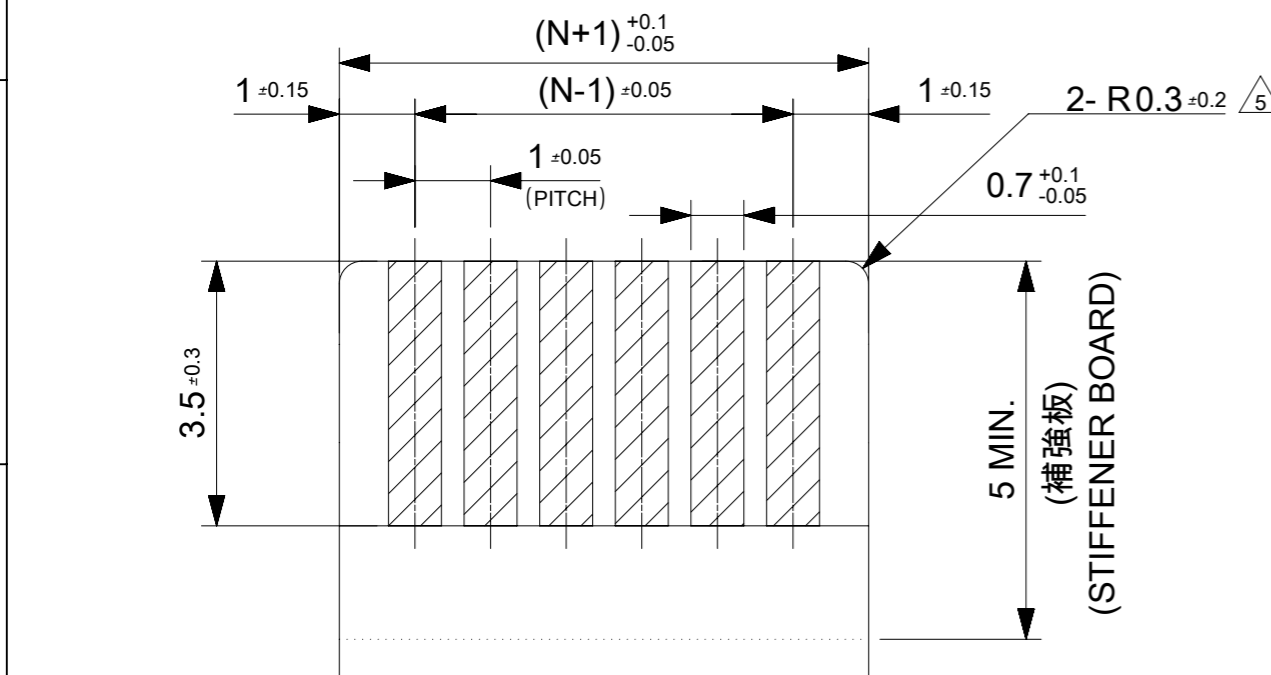
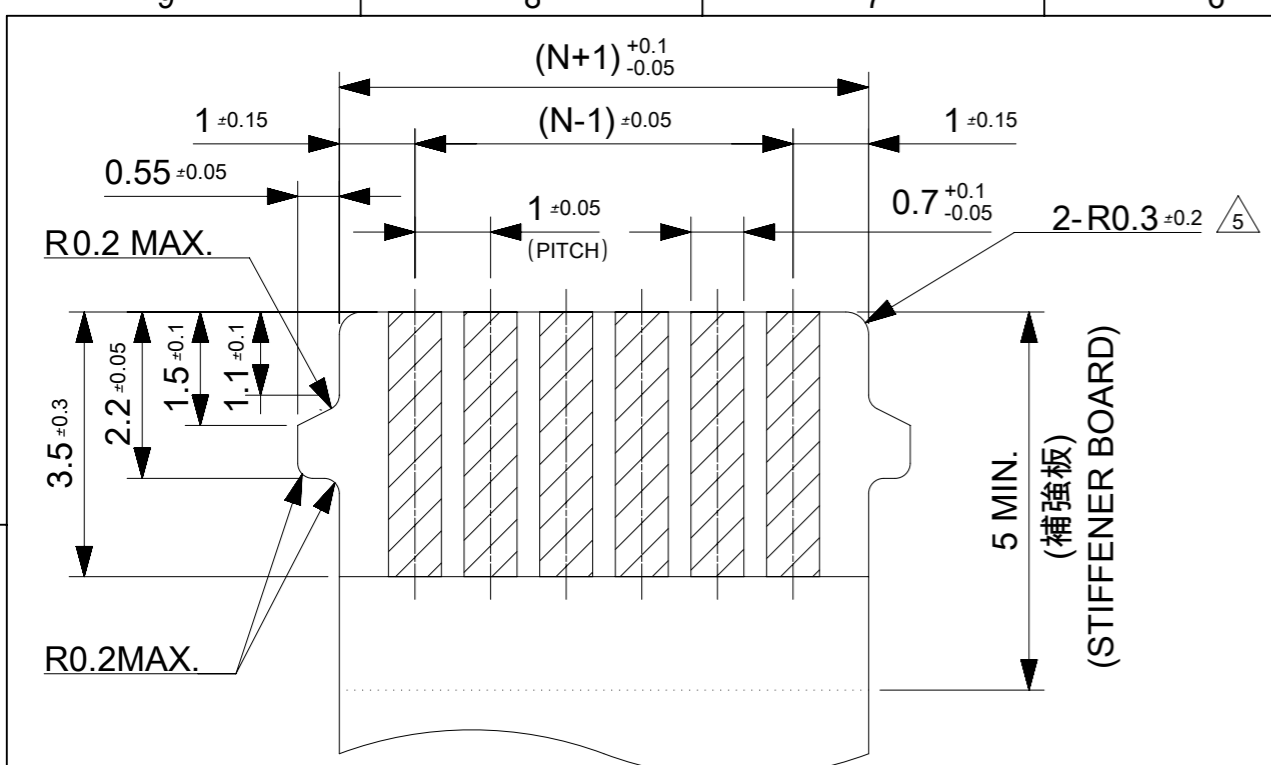


25.6	21	27.2	2005280220	22
20.6	16	22.2	2005280170	17
C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER NO.	Ckt

CONNECTOR SERIES NO. 2005281**0

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

REVISED	2016/04/25	2016/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE	molex [®]	
	EC NO: 103725	DRWN: MTAKAHASHI04		MM	10:1		
	CHK'D: KTAKAHASHI	APPR: YNOGAWA		ANGULAR TOL ± 1.0 °	DRWN BY: MTAKAHASHI04		DATE: 2015/12/21
	0 PLACES ± 0.2	1 PLACE ± 0.2		2 PLACES ± 0.2	3 PLACES ± 0.1		4 PLACES ± 0.05
REV	C	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION	A3	PRODUCT CUSTOMER DRAWING	
SERIES		MATERIAL NUMBER		CUSTOMER		1.0 FPC ZIF BTM 2 CONT HSG ASSY	
200528		SEE CHART		GENERAL			
DOCUMENT NUMBER			DOC TYPE	DOC PART	SHEET NUMBER		
2005281006			PSD	000	1 OF 3		



PRE-RELEASE REFERENCE USE ONLY

FPC構成推奨仕様
STRUCTURE OF FPC

FFC構成推奨仕様
STRUCTURE OF FFC

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REVISED	2016/04/25	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION UNITS	SCALE
	2016/04/25		MM	≠
EC NO: 103725 DRWN: MTAKAHASHI04 CHK'D: KTAKAHASHI APPR: YNOGAWA	4 PLACES	± 0.05	DRWN BY	DATE
	3 PLACES	± 0.1	MTAKAHASHI04	2015/12/21
	2 PLACES	± 0.2	CHK'D BY	DATE
	1 PLACE	± 0.2	KTAKAHASHI	2015/12/25
	0 PLACES	± 0.2	APPR BY	DATE
			YNOGAWA	2016/01/04
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION
			A3	

molex			
1.0 FPC ZIF BTM 2 CONT HSG ASSY			
PRODUCT CUSTOMER DRAWING			
SERIES	MATERIAL NUMBER	CUSTOMER	
200528	SEE SHEET 1	GENERAL	
DOCUMENT NUMBER		DOC TYPE	DOC PART SHEET NUMBER
2005281006		PSD	000 2 OF 3

注記 NOTES

1.使用材料 MATERIAL

ハウジング :液晶ポリマー ガラス充填、UL94V-0(ベージュ)
 HOUSING LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)
 アクチュエータ :ポリアミド ガラス充填、UL94V-0(黒)
 ACTUATOR POLYAMIDE GLASS FILLED, UL94V-0(BLACK)
 ターミナル :リン青銅(t=0.15)
 TERMINAL PHOSPHOR BRONZE
 金具 :リン青銅(t=0.15)
 FITTING NAIL PHOSPHOR BRONZE

2.めっき仕様 PLATING

ターミナル TERMINAL
 コンタクト部 :部分金めっき (0.1µm以上)
 テール部 :部分金めっき
 下地:ニッケルめっき (1.0µm以上)
 CONTACT AREA : SEPARATED GOLD PLATING (0.05 MICROMETER MINIMUM)
 SOLDER TAIL AREA : SEPARATED GOLD PLATING
 UNDERPLATE : NICKEL OVERALL (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 錫めっき(1.0µm以上)
 下地:ニッケルめっき (1.0µm以上)
 TIN PLATING (1.0 MICROMETER MIN.)
 UNDER PLATING : NICKEL PLATING (1.0 MICROMETER MIN.)

3.エンボステーブ梱包時は、アクチュエータが閉じた状態とする。
 IN THE PACKAGE, ACTUATOR OF PART SHOULD BE CLOSED.

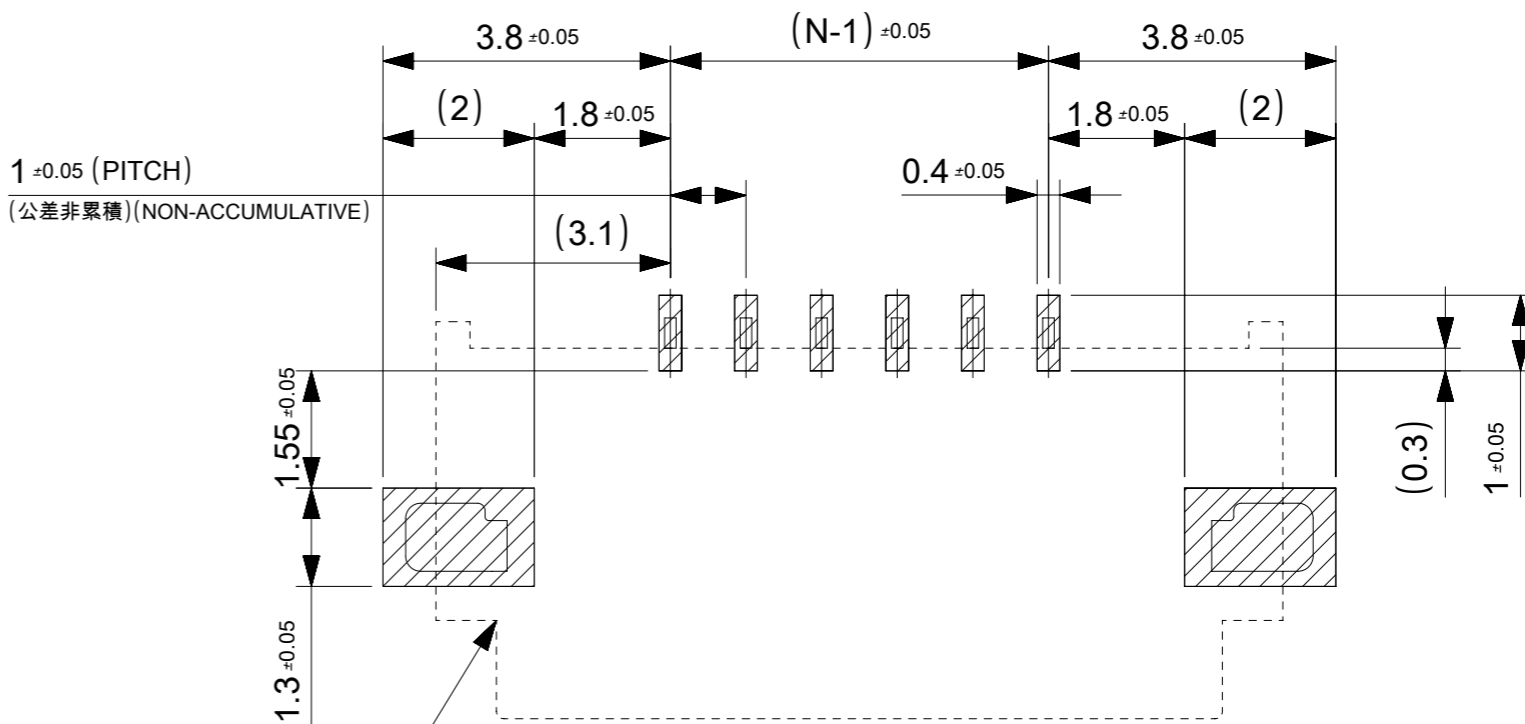
4. パターン剥離止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.

5. R0.3はFPC/FFC導体部にかからないこと。
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC/FFC.

6.N:極数 N:CIRCUIT.

7.ELV及びRoHS適合品
 ELV AND RoHS COMPLIANT

8.テールと金具を併せた平坦度は0.1以下とする。
 TAILS AND NAILS COPLANALITY TO BE 0.1 MAX.



コネクタ位置
 (CONNECTOR POSITION)

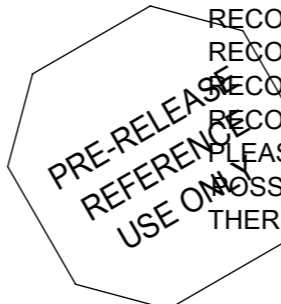
推奨基板レイアウト
 RECOMENDED P.W.B.
 PATTERN LAYOUT

参考マスク厚 : 100µm
 参考マスク開口率 : 100%
 REFERENCE SCREEN THICKNESS : 100µm
 REFERENCE SCREEN OPEN RATIO : 100%

FPC/FFCについて ABOUT FPC/FFC
 打ち抜き方向は導体側から補強板側を推奨します。
 導体部については軟箔銅35µmまたは50µmを推奨します。
 FFCに規定された定格温度がFFC単体前提である場合が御座います。
 コネクタと組み合わせた実使用において、接着層が劣化するなどの信頼性を満足できないケースを回避するため、
 実機での評価/確認をお願いいたします。

RECOMMENDED PUNCHING DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER SIDE
 RECOMMENDED CONDUCTOR SPEC : SOFT COPPER FOIL
 RECOMMENDED CONDUCTOR THICKNESS : 35 MICROMETER OR 50 MICROMETER
 WHEN ACTUALLY USING IT WITH CONNECTOR, PLEASE DO THE EVALUATION AND THE CONFIRMATION WITH AN ACTUAL EQUIPMENT TO EVADE THE CASE WHERE RELIABILITY CANNOT BE FILLED (THE ADHESIVE LINE OF FFC IS DETERIORATED ETC.)

FPCについて ABOUT FPC
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。
 RECOMMENDED MATERIAL/THICKNESS.
 RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
 RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
 RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.
 THERE IS A POSSIBILITY THAT THE PRESCRIPT TEMPERATURE OF FFC IS SET TO SINGLE IT.



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	2016/04/25		MM	±±			
	EC NO: 103725 DRWN: MTAKAHASHI04 CHK'D: KTAKAHASHI APPR:		4 PLACES	± 0.05		DRWN BY	DATE
			3 PLACES	± 0.1		MTAKAHASHI04	2015/12/21
2 PLACES		± 0.2	CHK'D BY	DATE			
		1 PLACE	± 0.2	KTAKAHASHI	2015/12/25		
		0 PLACES	± 0.2	APPR BY	DATE		
				YNOGAWA	2016/01/04		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DRAWING SIZE	THIRD ANGLE PROJECTION			
			A3				

PRODUCT CUSTOMER DRAWING		
SERIES	MATERIAL NUMBER	CUSTOMER
200528	SEE SHEET 1	GENERAL
DOCUMENT NUMBER	DOC TYPE	DOC PART
2005281006	PSD	000
SHEET NUMBER		
3 OF 3		